

Features

Wide IF Bandwidth: DC - 3.5 GHz

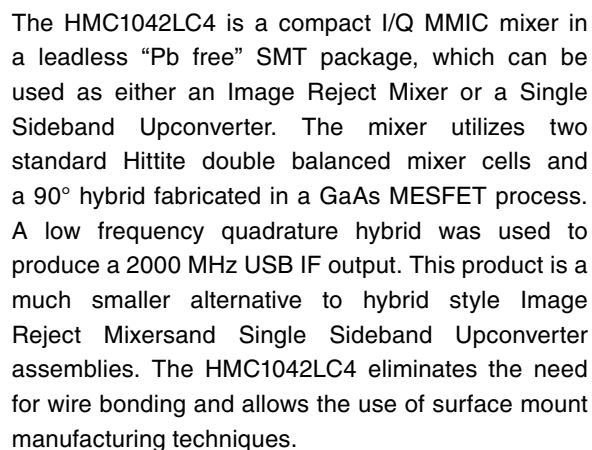
- Image Rejection: 30 dBc

LO to RF Isolation: 40 dB

High Input IP3: +22 dBm

24 Lead 4 x 4 mm SMT Package: 16 mm²

General Description



Parameter	Min.	Typ.	Max.	Min.	Typ.	Max.	Units
Frequency Range, RF/LO	15 - 25			25 - 33.5			GHz
Frequency Range, IF	DC - 3.5			DC - 3.5			GHz
Conversion Loss (As IRM)		9	12		11	14	dB
Image Rejection	16	24		16	30		dB
LO to RF Isolation	35	40		33	43		dBc
LO to IF Isolation		35			45		dB
IP3 (Input)		20			22		dBm
Amplitude Balance ^[2] ^[3]		±0.5			±0.5		dB
Phase Balance ^[2] ^[3]		±2.5			±2.5		Deg

[3] *Data taken with IF = 100 MHz*

HMC1042* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS

View a parametric search of comparable parts.

EVALUATION KITS

- HMC1042LC4 Evaluation Board

DOCUMENTATION

Data Sheet

- HMC1042 Data Sheet

REFERENCE MATERIALS

Quality Documentation

- Semiconductor Qualification Test Report: MESFET-B (QTR: 2013-00245)

DESIGN RESOURCES

- HMC1042 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC1042 EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK

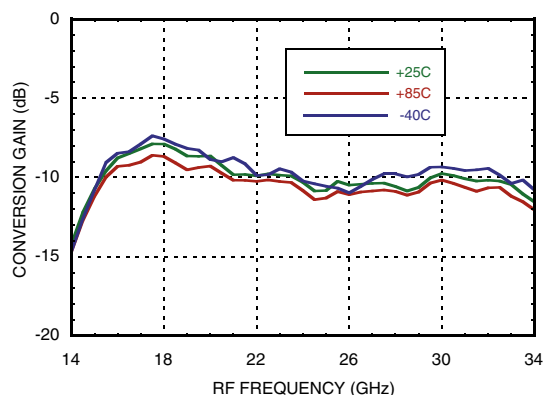
Submit feedback for this data sheet.



**GaAs MMIC I/Q MIXER
15 - 33.5 GHz**

Data Taken As IRM with External IF 90° Hybrid, IF = 2000 MHz

Conversion Gain, USB vs. Temperature



Conversion Gain, USB vs. LO Drive

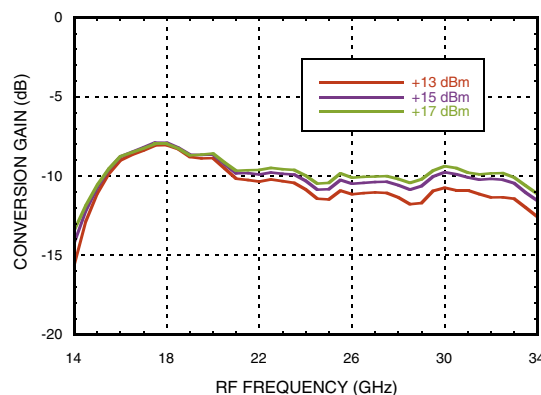


Image Rejection, USB vs. Temperature

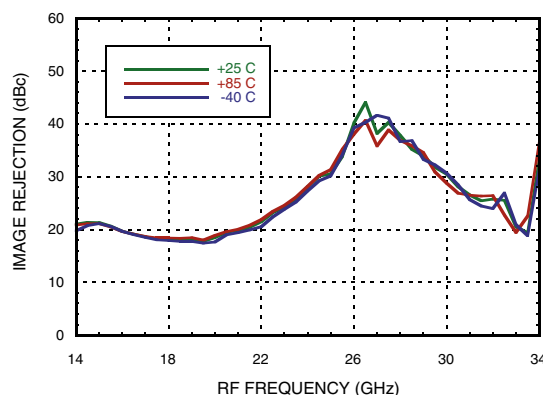
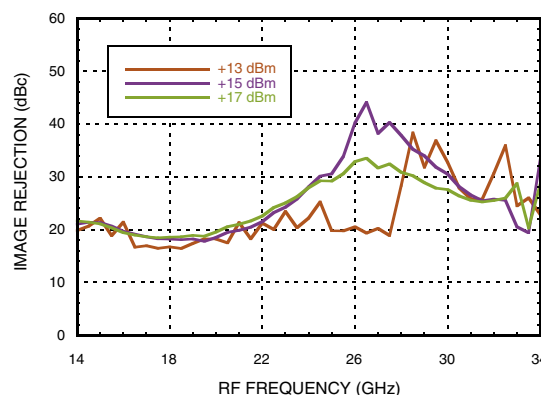
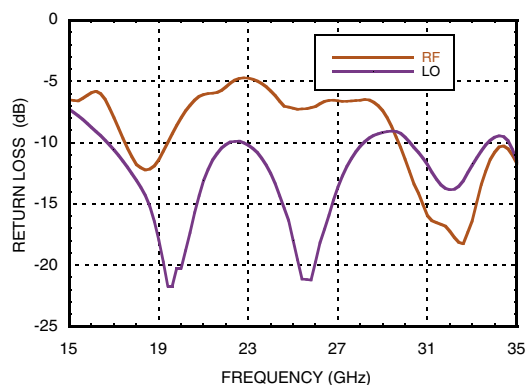


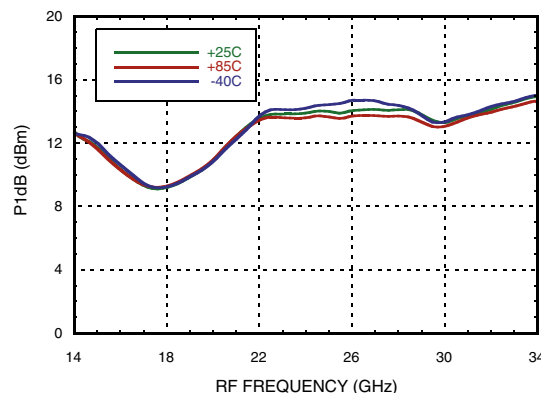
Image Rejection, USB vs. LO Drive



Return Loss ^[1]



Input P1dB, USB vs. Temperature



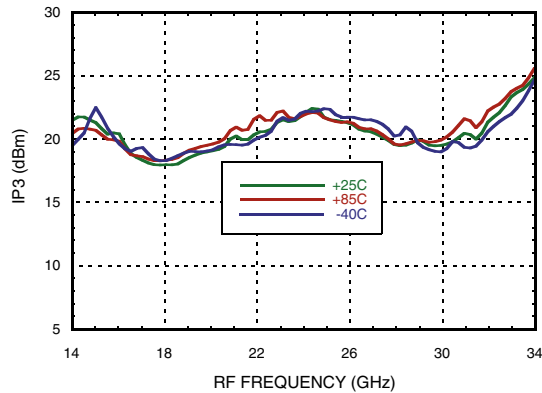
[1] Data taken without external 90° hybrid.



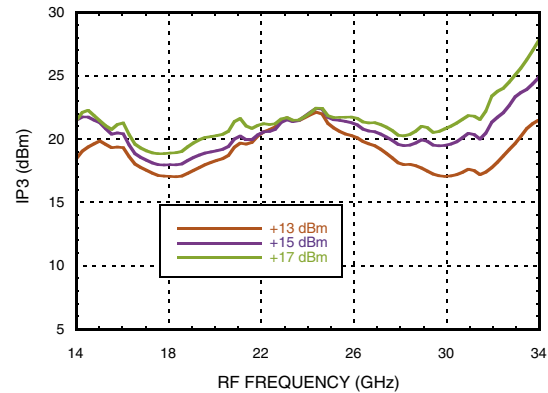
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15 - 33.5 GHz**

Data Taken As IRM with External IF 90° Hybrid, IF = 2000 MHz

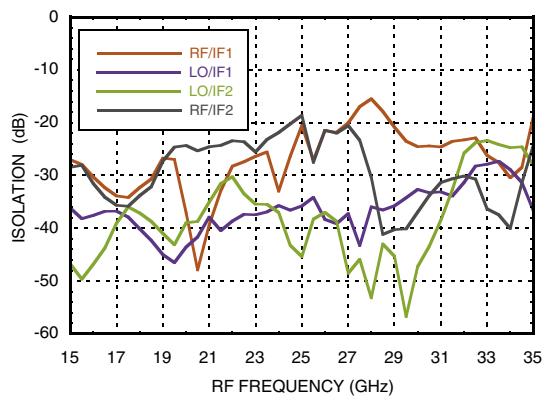
Input IP3, USB vs. Temperature



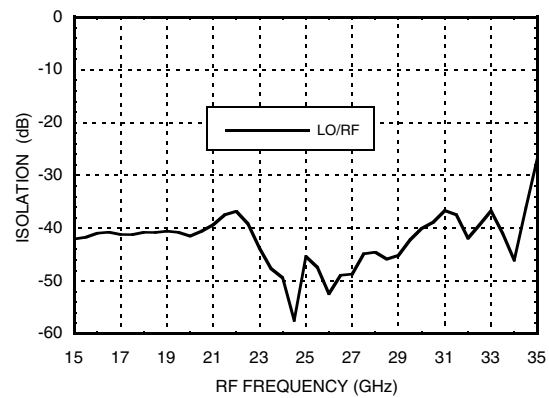
Input IP3, USB vs LO Drive



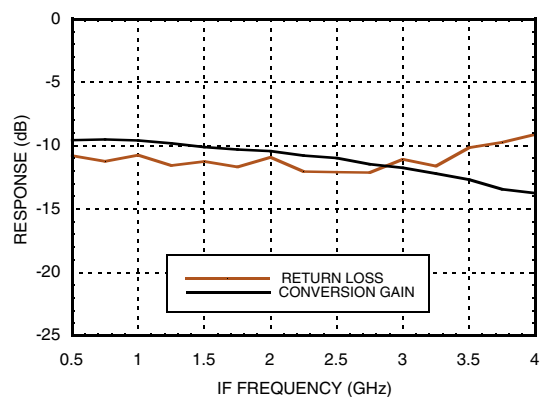
Isolation



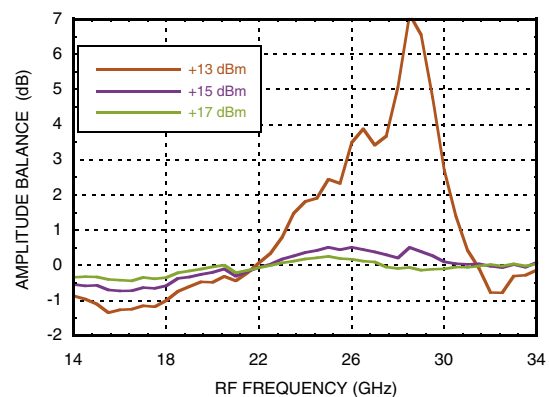
LO/RF Isolation



IF Bandwidth ^[1]



Amplitude Balance, USB vs. LO Drive ^{[1] [2]}



[1] Data taken without external 90° hybrid.

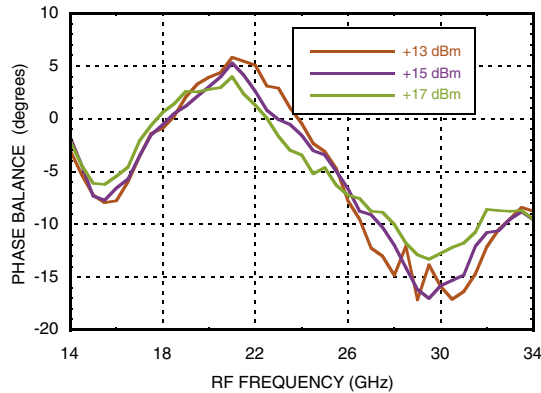
[2] Data taken with IF = 100 MHz.



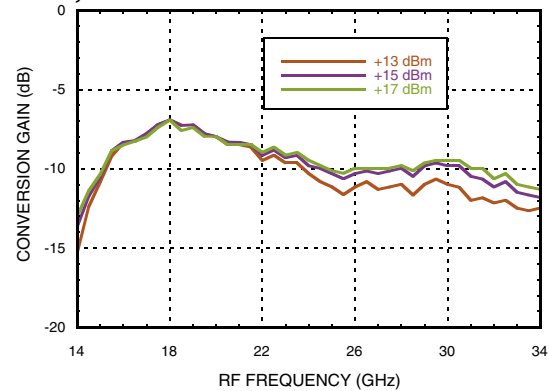
**GaAs MMIC I/Q MIXER
15 - 33.5 GHz**

Data Taken As IRM with External IF 90° Hybrid, IF = 2000 MHz

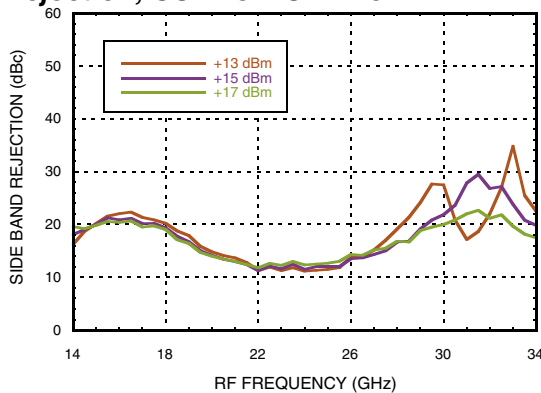
Phase Balance, USB vs. LO Drive [1] [2]



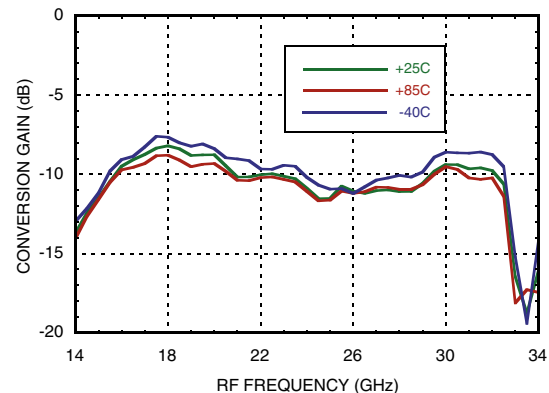
Upconverter Performance Conversion Gain, USB vs. LO Drive



Upconverter Performance Sideband Rejection, USB vs. LO Drive



Conversion Gain, LSB vs. Temperature



Conversion Gain, LSB vs. LO Drive

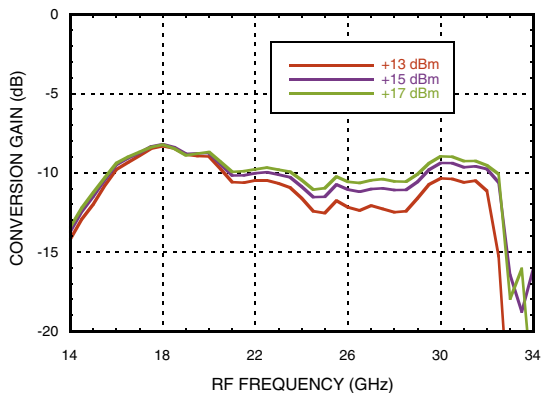
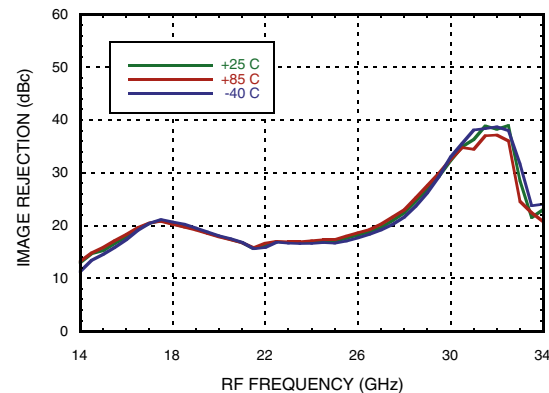


Image Rejection, LSB vs. Temperature



[1] Data taken without external 90° hybrid.

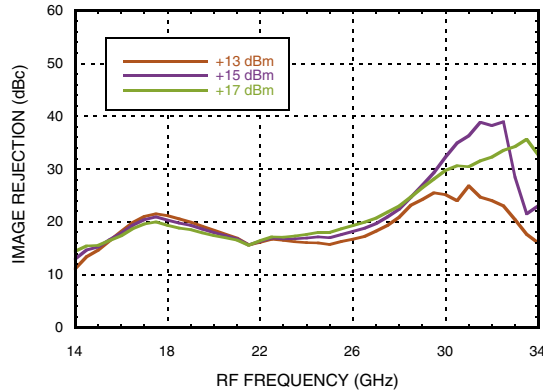
[2] Data taken with IF = 100 MHz.



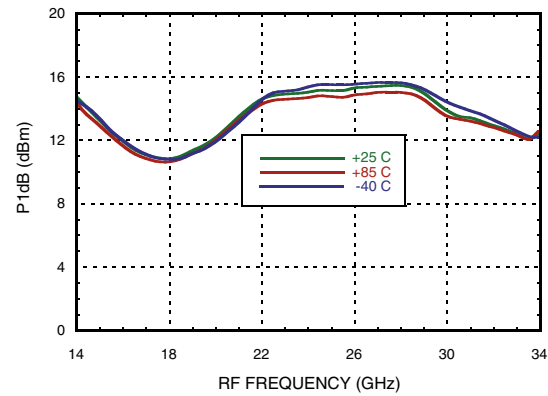
**GaAs MMIC I/Q MIXER
15 - 33.5 GHz**

Data Taken As IRM with External IF 90° Hybrid, IF = 2000 MHz

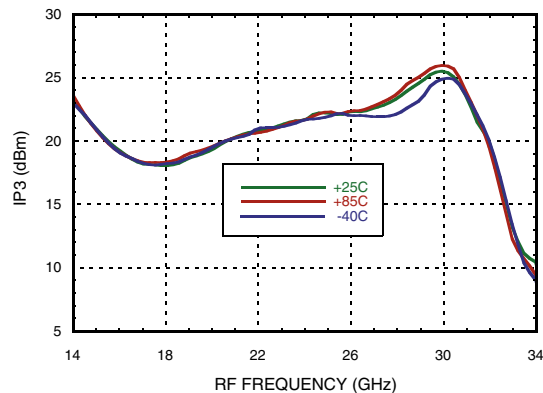
Image Rejection, LSB vs. LO Drive



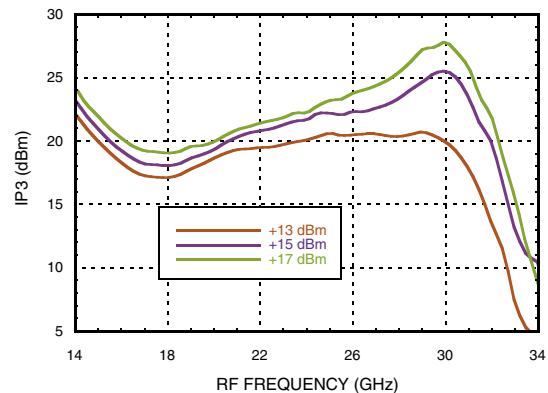
Input P1dB, LSB vs. Temperature



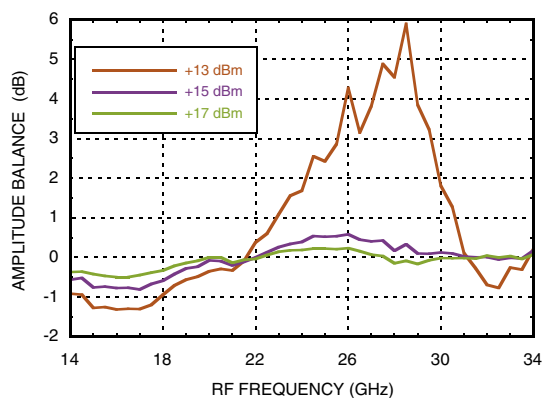
Input IP3, LSB vs. Temperature



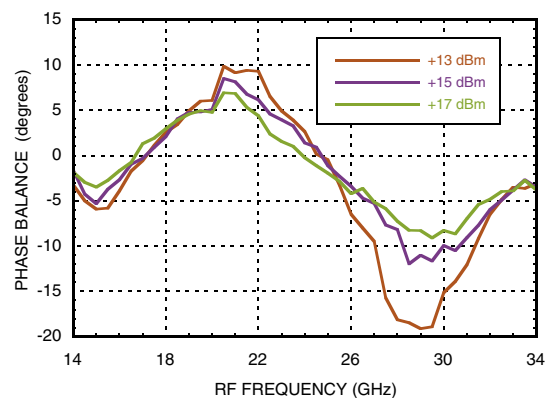
Input IP3, LSB vs LO Drive



Amplitude Balance, LSB vs. LO Drive ^{[1] [2]}



Phase Balance, LSB vs. LO Drive ^{[1] [2]}



[1] Data taken without external 90° hybrid.

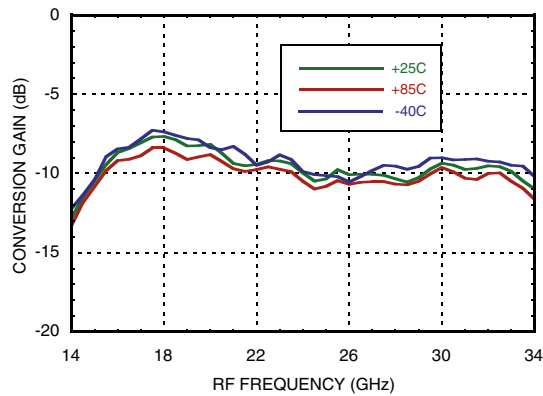
[2] Data taken with IF = 100 MHz.



**GaAs MMIC I/Q MIXER
15 - 33.5 GHz**

Data Taken As IRM with External IF 90° Hybrid, IF = 1000 MHz

Conversion Gain, USB vs. Temperature



Conversion Gain, USB vs. LO Drive

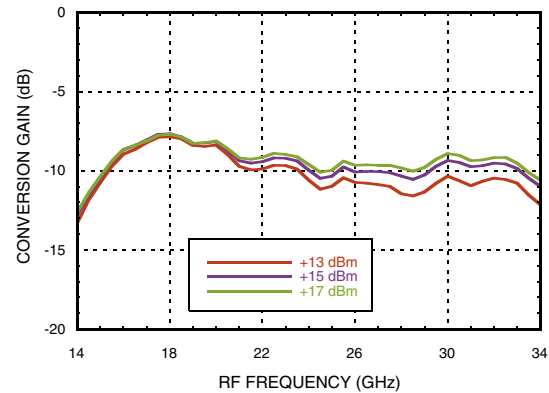


Image Rejection, USB vs. Temperature

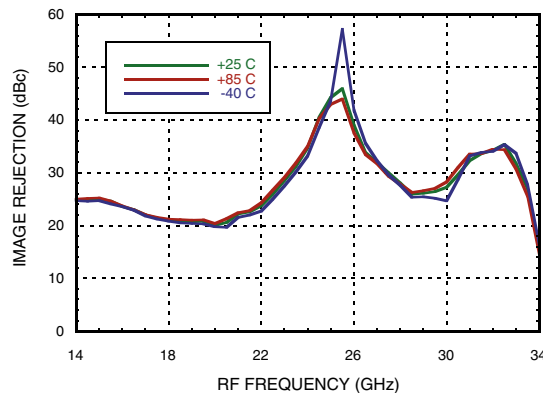
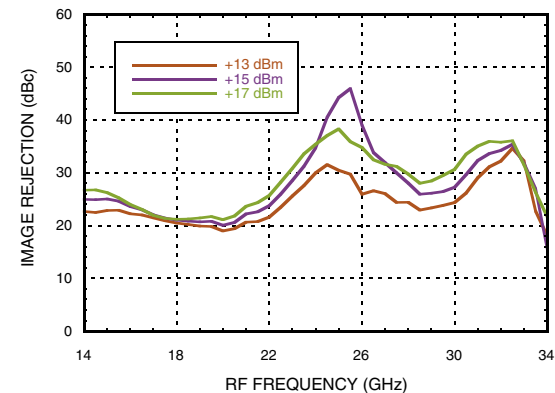
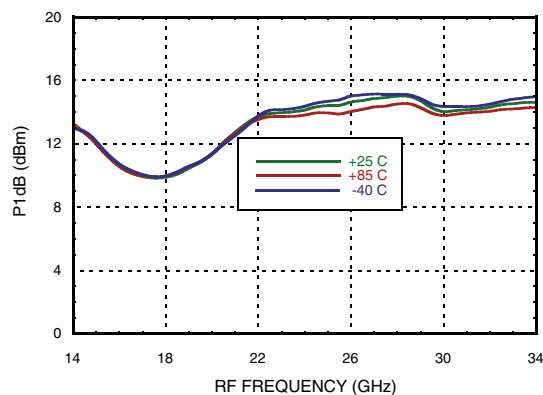


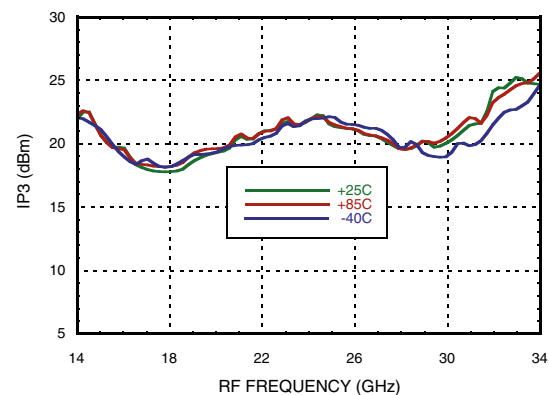
Image Rejection, USB vs. LO Drive



Input P1dB, USB vs. Temperature



Input IP3, USB vs. Temperature

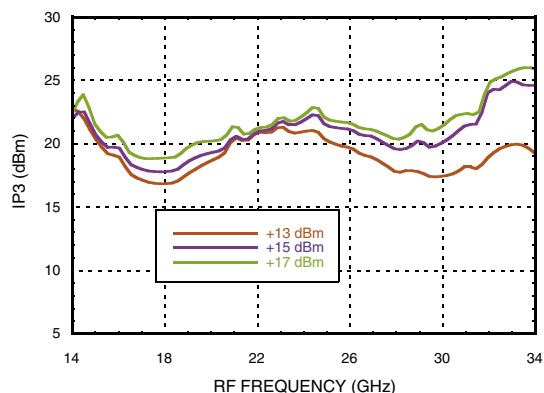




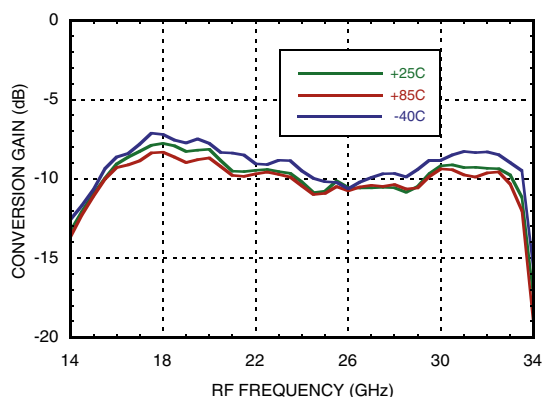
**GaAs MMIC I/Q MIXER
15 - 33.5 GHz**

Data Taken As IRM with External IF 90° Hybrid, IF = 1000 MHz

Input IP3, USB vs LO Drive



Conversion Gain, LSB vs. Temperature



Conversion Gain, LSB vs. LO Drive

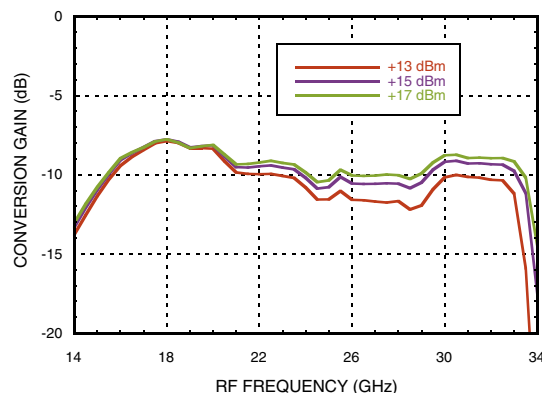


Image Rejection, LSB vs. Temperature

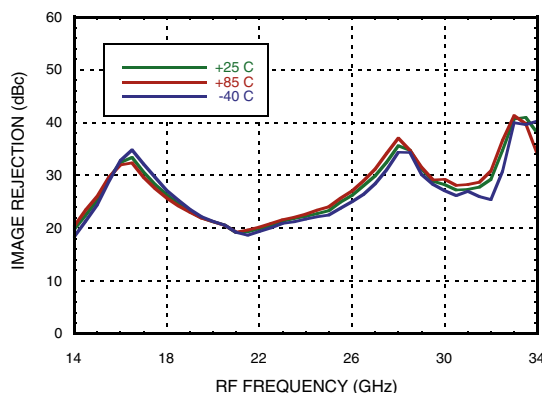
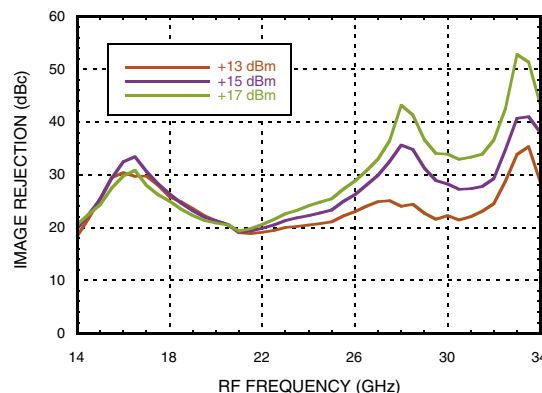


Image Rejection, LSB vs. LO Drive

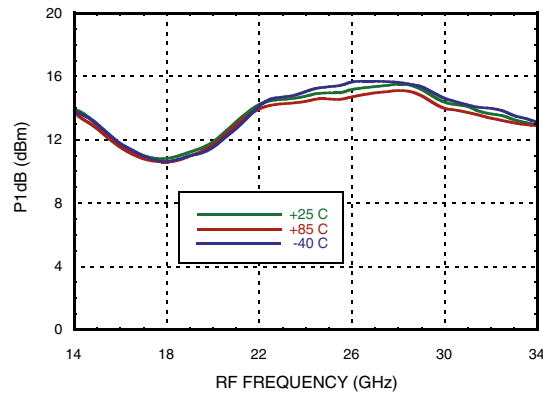




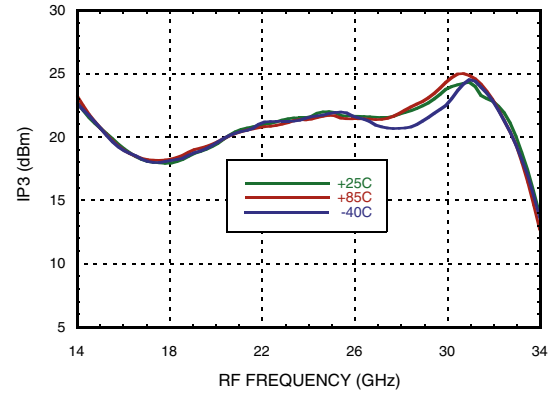
**GaAs MMIC I/Q MIXER
15 - 33.5 GHz**

Data Taken As IRM with External IF 90° Hybrid, IF = 1000 MHz

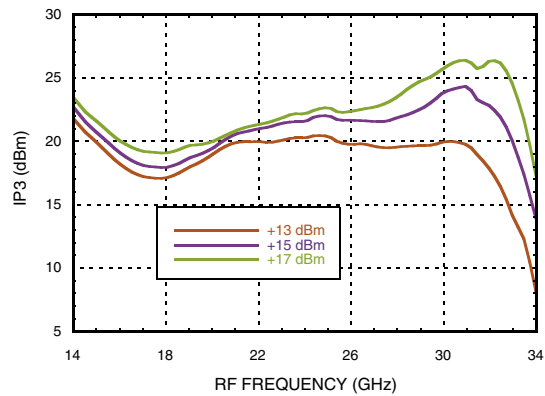
Input P1dB, LSB vs. Temperature



Input IP3, LSB vs. Temperature



Input IP3, LSB vs LO Drive

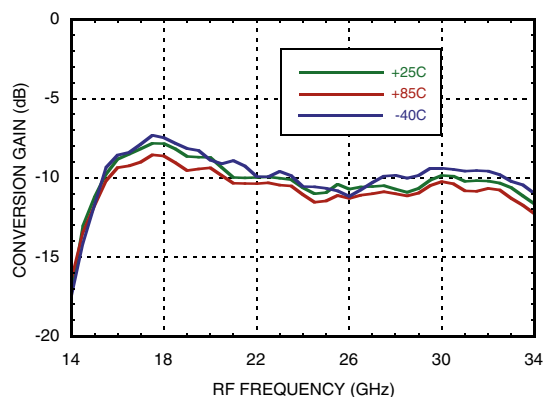




**GaAs MMIC I/Q MIXER
15 - 33.5 GHz**

Data Taken As IRM with External IF 90° Hybrid, IF = 2500 MHz

Conversion Gain, USB vs. Temperature



Conversion Gain, USB vs. LO Drive

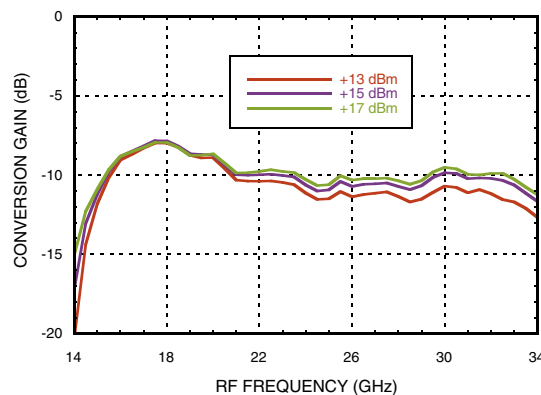


Image Rejection, USB vs. Temperature

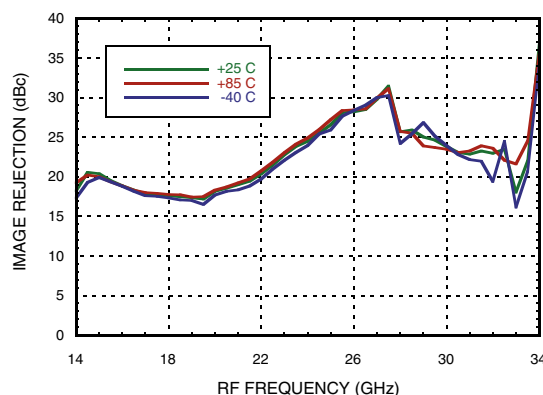
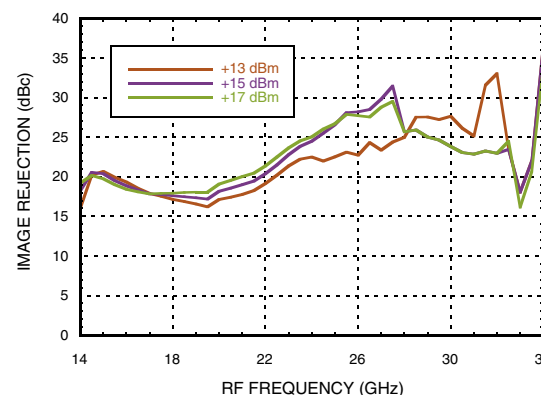
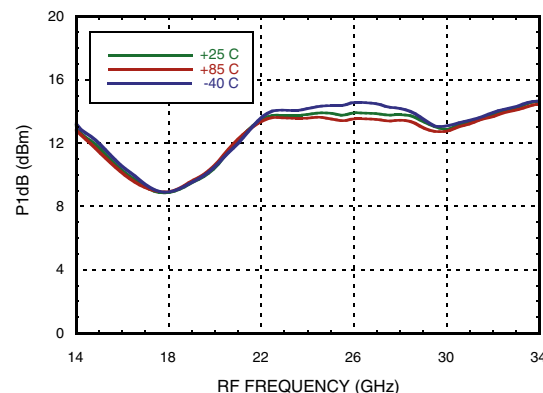


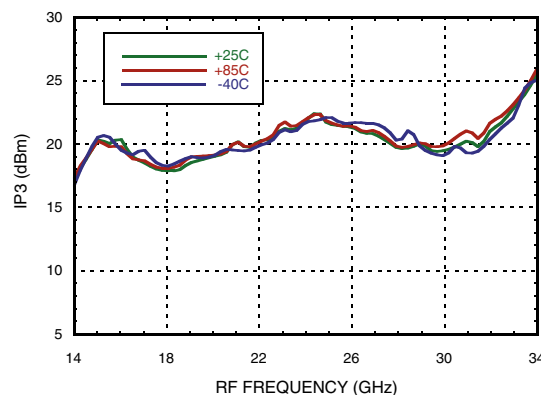
Image Rejection, USB vs. LO Drive



Input P1dB, USB vs. Temperature



Input IP3, USB vs. Temperature

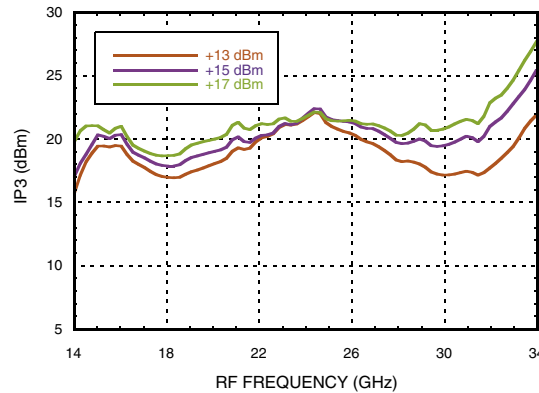




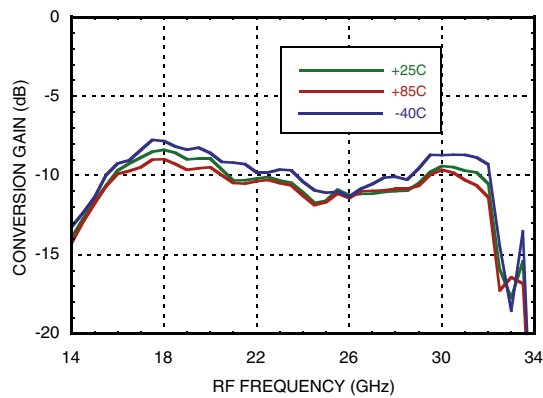
**GaAs MMIC I/Q MIXER
15 - 33.5 GHz**

Data Taken As IRM with External IF 90° Hybrid, IF = 2500 MHz

Input IP3, USB vs. Temperature



Conversion Gain, LSB vs. Temperature



Conversion Gain, LSB vs. LO Drive

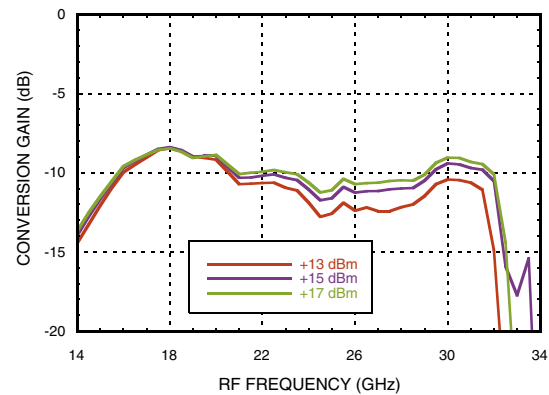


Image Rejection, LSB vs. Temperature

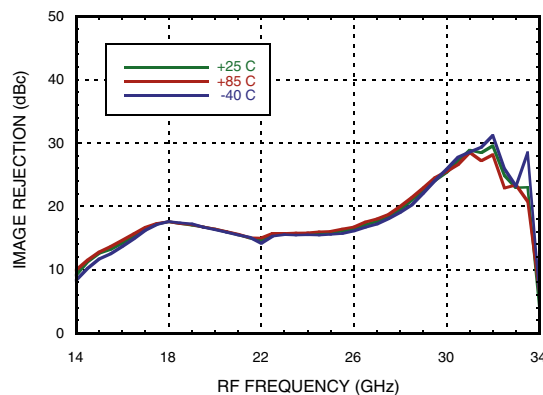
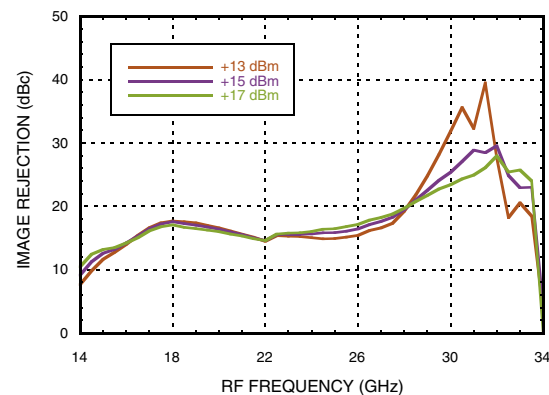


Image Rejection, LSB vs. LO Drive

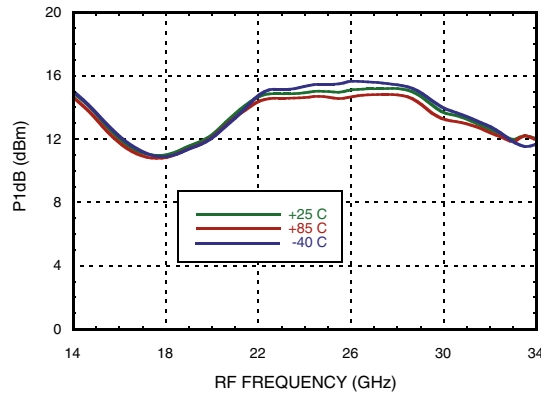




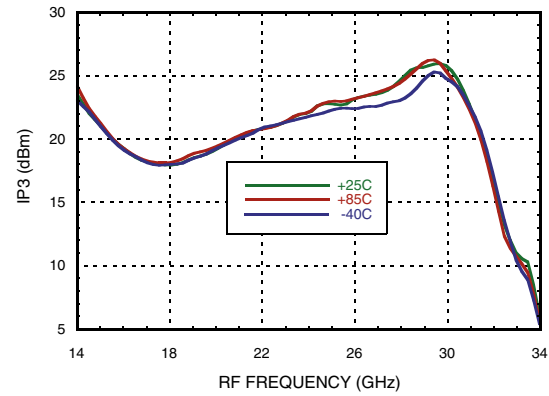
**GaAs MMIC I/Q MIXER
15 - 33.5 GHz**

Data Taken As IRM with External IF 90° Hybrid, IF = 2500 MHz

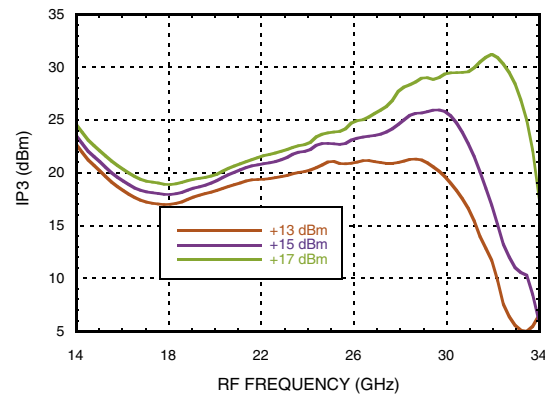
Input P1dB, LSB vs. Temperature



Input IP3, LSB vs. Temperature



Input IP3, LSB vs LO Drive





Harmonics of LO

LO Freq. (GHz)	nLO Spur at RF Port		
	1	2	3
13	43	40	45
18	41	50	X
23	44	44	X
28	44	X	X
33	36	X	X

LO = +15 dBm
Values in dBc below LO level measured at RF Port.

MxN Spurious Outputs

mRF	nLO				
	0	1	2	3	4
0		14	34	25	X
1	21	X	38	58	66
2	81	82	63	64	85
3	67	79	84	82	88
4	X	65	76	85	89

RF = 25 GHz @ -10 dBm
LO = 23 GHz @ +11 dBm
Data taken without IF hybrid
All values in dBc below IF power level

Absolute Maximum Ratings

RF / IF Input (LO = +18 dBm)	+18 dBm
LO Drive	+20 dBm
Channel Temperature	150 °C
Continuous Pdiss (T = 85 °C) (derate 5.0 mW/°C above 85 °C)	328 mW
Thermal Resistance (R _{TH}) (junction to package bottom)	198 °C/W
Storage Temperature	-65 to +125 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A

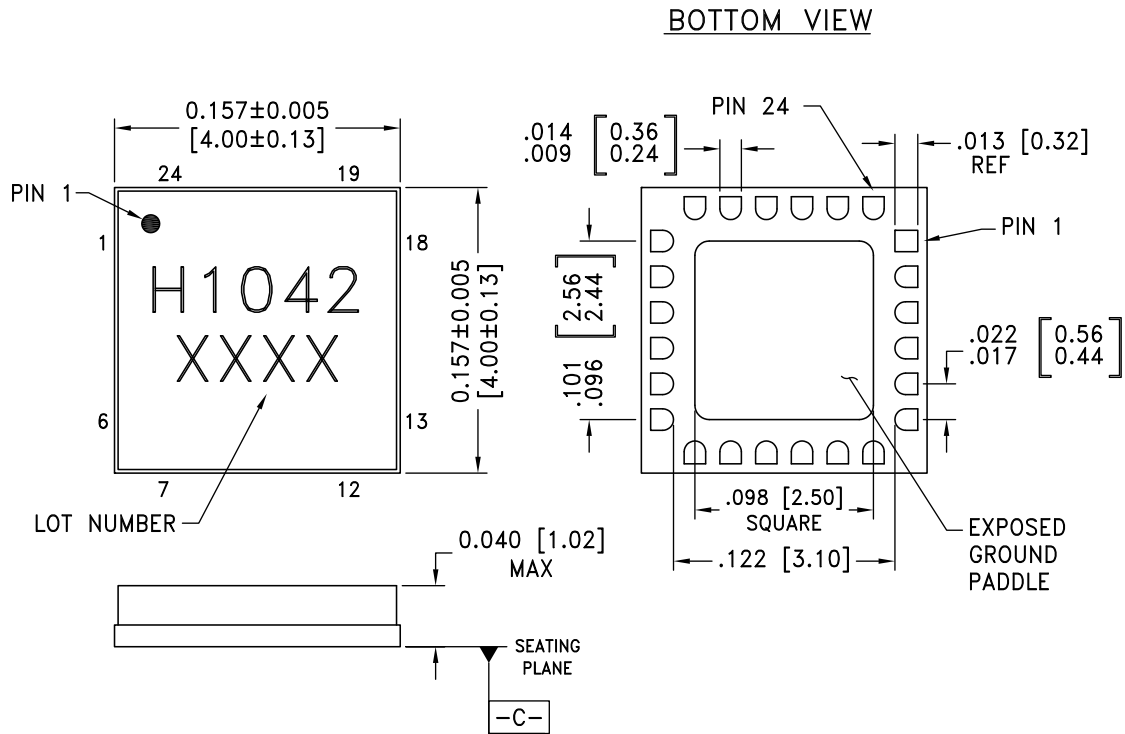


**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**



**GaAs MMIC I/Q MIXER
15 - 33.5 GHz**

Outline Drawing



NOTES:

1. PACKAGE BODY MATERIAL: ALUMINA.
2. LEAD AND GROUND PADDLE PLATING: GOLD FLASH OVER NICKEL.
3. DIMENSIONS ARE IN INCHES (MILLIMETERS).
4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
5. PACKAGE WARP SHALL NOT EXCEED 0.05 MM DATUM -C-
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.


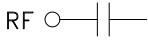
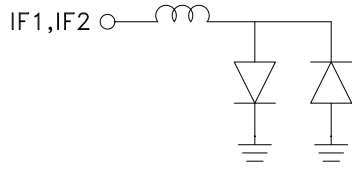

Package Information

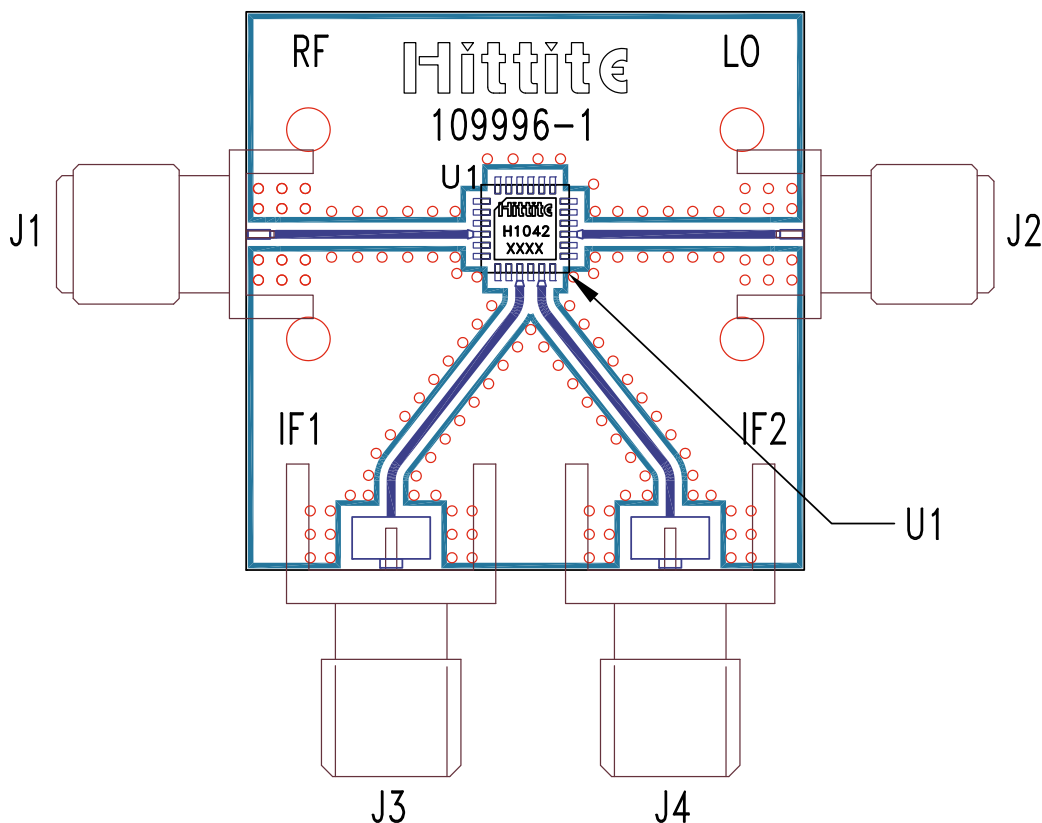
Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[2]
HMC1042LC4	Alumina, White	Gold over Nickel	MSL3 ^[1]	H1042 XXXX

[1] Max peak reflow temperature of 260 °C

[2] 4-Digit lot number XXXX


**GaAs MMIC I/Q MIXER
15 - 33.5 GHz**
Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 2, 6, 7, 10, 12, 13, 17-24	N/C	These pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally.	
3, 5, 8, 14, 16	GND	These pins and the exposed ground paddle must be connected to RF/DC ground.	
4	RF	This pin is AC coupled and matched to 50 Ohms.	
9	IF2	This pin is DC coupled. For application not requiring operation to DC, this port should be DC blocked externally using a series capacitor whose value has been chosen to pass the necessary IF frequency range. For operation to DC, this pin must not source/sink more than 3 mA of current or product non-function and possible product failure will result.	
11	IF1		
15	LO	This pin is AC coupled and matched to 50 Ohms from 15 to 33.5 GHz	


**GaAs MMIC I/Q MIXER
15 - 33.5 GHz**
Evaluation PCB

List of Materials for Evaluation PCB EVAL01-HMC1042LC4 ^[1]

Item	Description
J1, J2	PCB Mount SMA RF Connector, SRI
J3 - J4	PCB Mount SMA Connector, Johnson
U1	HMC1042LC4
PCB ^[2]	109996-1 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

**Notes**